

2SK214-VB Datasheet

N-Channel 150-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY

| V_{DS} (V) | $R_{DS(on)}$ (Ω) | I_D (A) |
|--------------|---------------------------|-----------|
| 150 | 0.030 at $V_{GS} = 10$ V | 50 |
| | 0.033 at $V_{GS} = 6$ V | 45 |

FEATURES

- Trench Power MOSFETs
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC


RoHS
 COMPLIANT

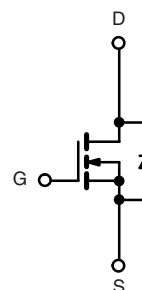
APPLICATIONS

- Primary Side Switch

TO-220AB



Top View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------------|------|
| Drain-Source Voltage | V_{DS} | 150 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | |
| Continuous Drain Current ($T_J = 175$ °C) | I_D | 50 | A |
| | | 35 | |
| Pulsed Drain Current | I_{DM} | 150 | |
| Avalanche Current | I_{AR} | 50 | |
| Repetitive Avalanche Energy ^a | E_{AR} | 80 | mJ |
| Maximum Power Dissipation ^a | P_D | 166 ^b | W |
| | | 3.75 | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to 175 | °C |

THERMAL RESISTANCE RATINGS

| Parameter | Symbol | Limit | Unit |
|----------------------------------|------------|-------|------|
| Junction-to-Ambient ^c | R_{thJA} | 40 | °C/W |
| Junction-to-Case (Drain) | R_{thJC} | 0.9 | |

Notes:

a. Duty cycle ≤ 1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

| SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted | | | | | | |
|--|---------------|---|------|-------|-----------|---------------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{DS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 150 | | | V |
| Gate-Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 2 | | 4 | |
| Gate-Body Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 120\text{ V}, V_{GS} = 0\text{ V}$ | | | 1 | μA |
| | | $V_{DS} = 120\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^{\circ}\text{C}$ | | | 50 | |
| | | $V_{DS} = 120\text{ V}, V_{GS} = 0\text{ V}, T_J = 175\text{ }^{\circ}\text{C}$ | | | 250 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$ | 80 | | | A |
| Drain-Source On-State Resistance ^a | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 15\text{ A}$ | | 0.030 | | Ω |
| | | $V_{GS} = 6\text{ V}, I_D = 10\text{ A}$ | | 0.033 | | |
| | | $V_{GS} = 10\text{ V}, I_D = 15\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$ | | 0.076 | | |
| | | $V_{GS} = 10\text{ V}, I_D = 15\text{ A}, T_J = 175\text{ }^{\circ}\text{C}$ | | 0.100 | | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = 15\text{ V}, I_D = 15\text{ A}$ | 10 | | | S |
| Dynamic ^b | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$ | | 2500 | | pF |
| Output Capacitance | C_{oss} | | | 290 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 190 | | |
| Gate Resistance | R_g | | | 2 | | Ω |
| Total Gate Charge ^c | Q_g | $V_{DS} = 75\text{ V}, V_{GS} = 10\text{ V}, I_D = 40\text{ A}$ | | 38 | 60 | nC |
| Gate-Source Charge ^c | Q_{gs} | | | 13 | | |
| Gate-Drain Charge ^c | Q_{gd} | | | 13 | | |
| Turn-On Delay Time ^c | $t_{d(on)}$ | $V_{DD} = 75\text{ V}, R_L = 1.80\text{ }\Omega$ $I_D \cong 40\text{ A}, V_{GEN} = 10\text{ V}, R_g = 2.5\text{ }\Omega$ | | 15 | 25 | ns |
| Rise Time ^c | t_r | | | 130 | 200 | |
| Turn-Off Delay Time ^c | $t_{d(off)}$ | | | 30 | 45 | |
| Fall Time ^c | t_f | | | 90 | 140 | |
| Source-Drain Diode Ratings and Characteristics $T_C = 25\text{ }^{\circ}\text{C}$ ^b | | | | | | |
| Continuous Current | I_S | | | | 40 | A |
| Pulsed Current | I_{SM} | | | | 80 | |
| Forward Voltage ^a | V_{SD} | $I_F = 40\text{ A}, V_{GS} = 0\text{ V}$ | | 1.0 | 1.5 | V |
| Reverse Recovery Time | t_{rr} | $I_F = 40\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$ | | 100 | 150 | ns |
| Peak Reverse Recovery Current | $I_{RM(REC)}$ | | | 5 | 8 | A |
| Reverse Recovery Charge | Q_{rr} | | | 0.25 | 0.6 | μC |

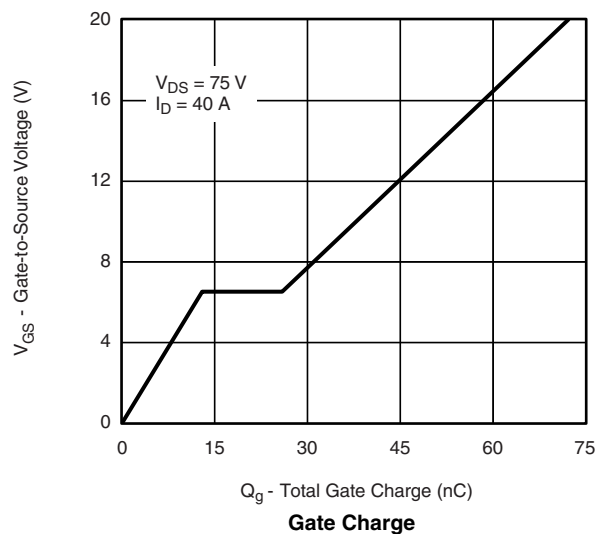
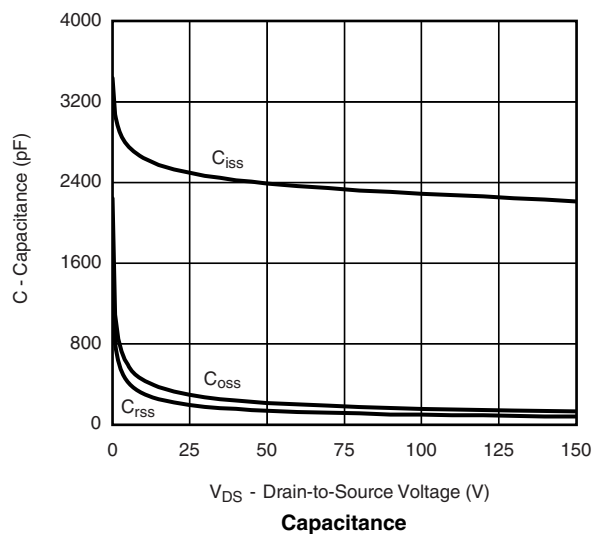
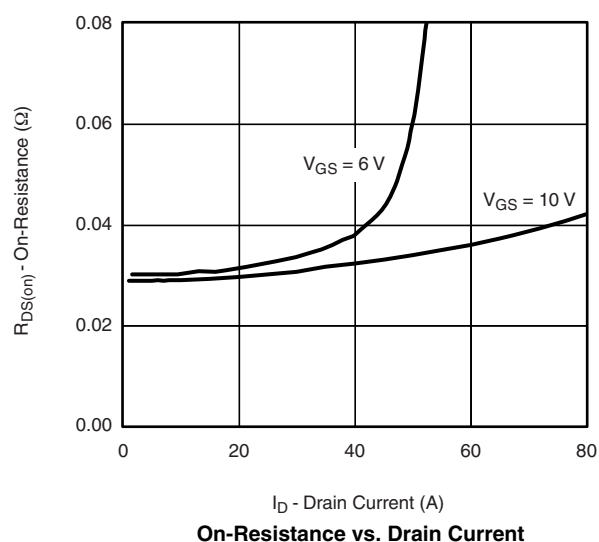
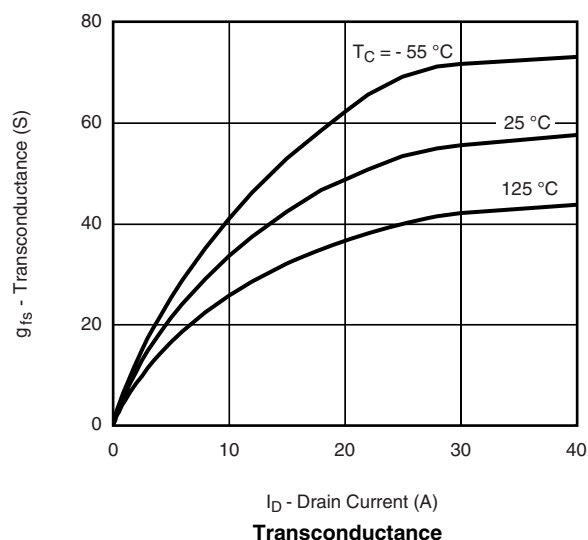
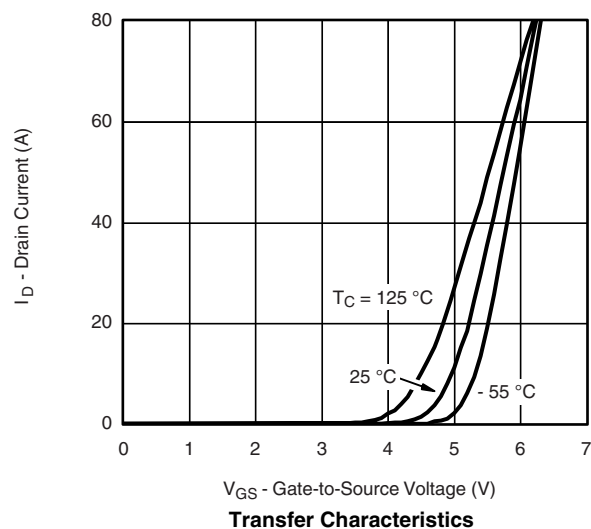
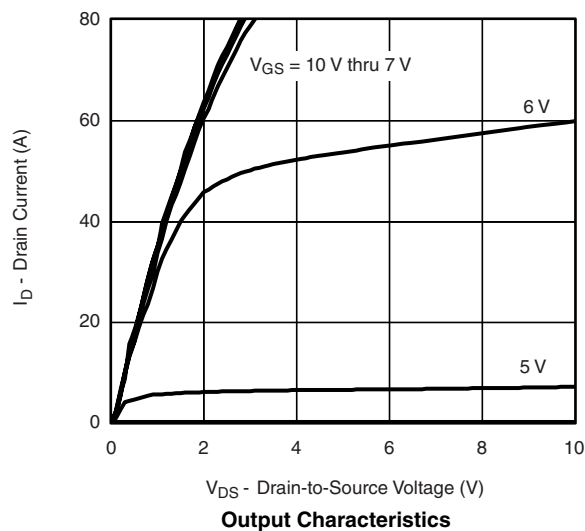
Notes:

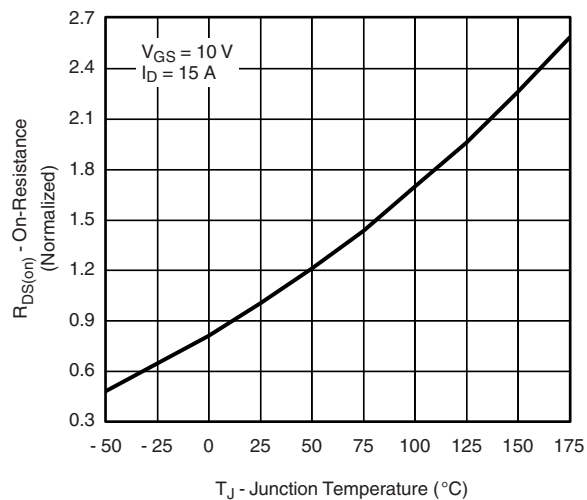
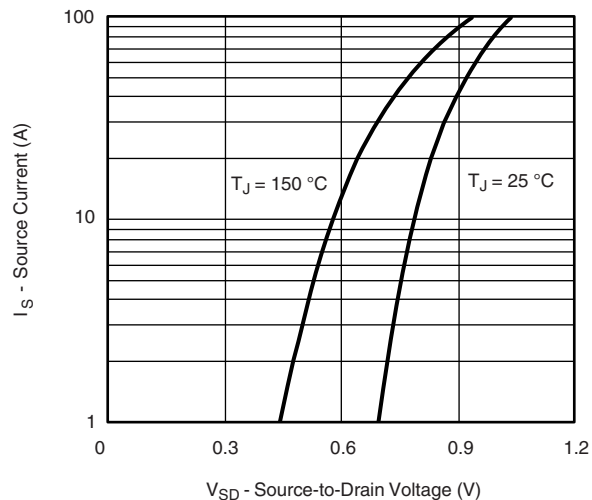
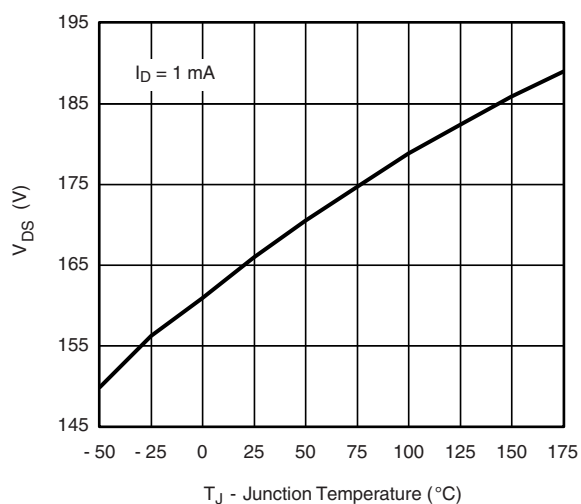
a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

b. Guaranteed by design, not subject to production testing.

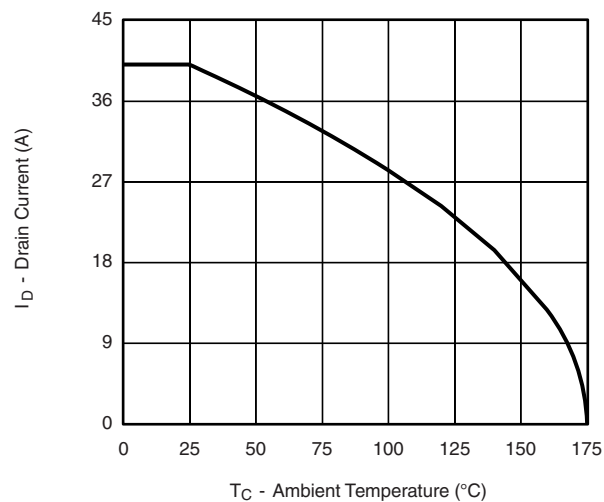
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

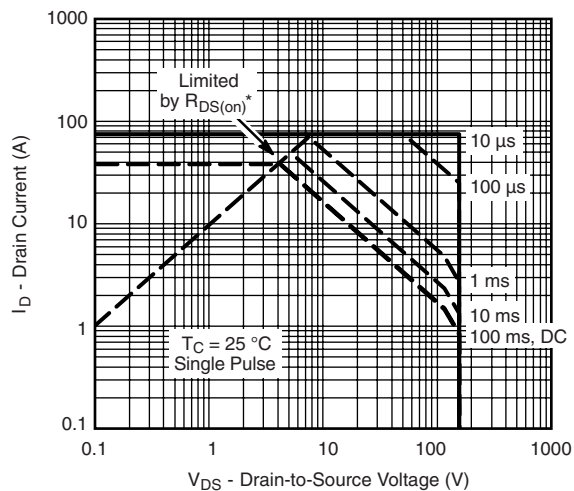
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted


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On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

**Drain Source Breakdown
vs. Junction Temperature**

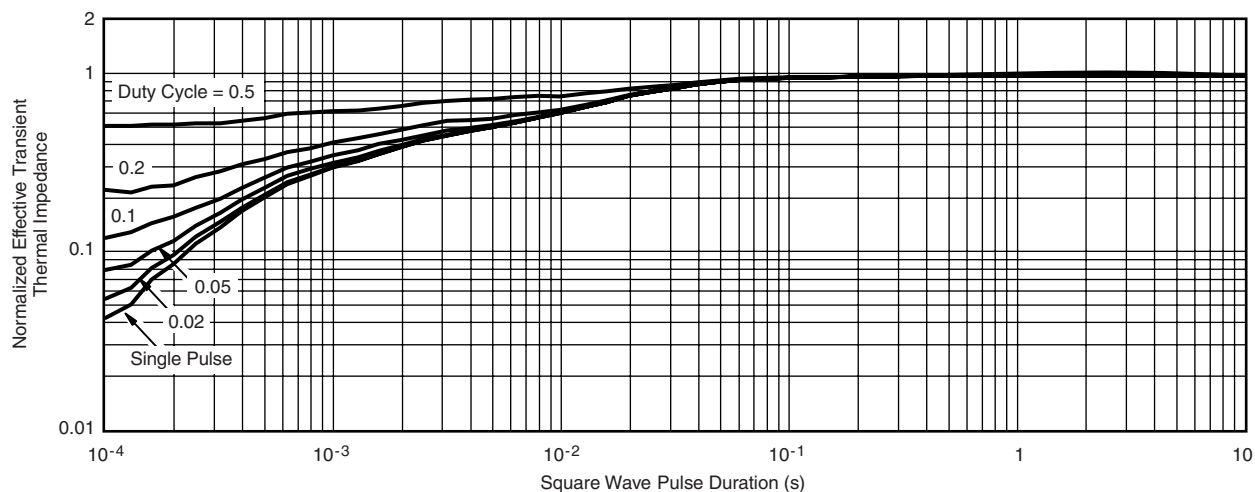
THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature



Safe Operating Area
 * $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



Normalized Thermal Transient Impedance, Junction-to-Case

TO-220AB



| DIM. | MILLIMETERS | | INCHES | |
|--|-------------|-------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.25 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.01 | 0.027 | 0.040 |
| b(1) | 1.20 | 1.73 | 0.047 | 0.068 |
| c | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.85 | 15.49 | 0.585 | 0.610 |
| E | 10.04 | 10.51 | 0.395 | 0.414 |
| e | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.09 | 6.48 | 0.240 | 0.255 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.35 | 14.02 | 0.526 | 0.552 |
| L(1) | 3.32 | 3.82 | 0.131 | 0.150 |
| $\varnothing P$ | 3.54 | 3.94 | 0.139 | 0.155 |
| Q | 2.60 | 3.00 | 0.102 | 0.118 |
| ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471 | | | | |

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM

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